

# MLCC with Dipped Radial Lead

## FA23X7R1E226MNU00



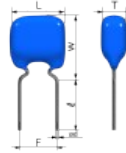
**Applications** Automotive Grade

**Feature**

- General** General (Up to 50V)
- Halogen-free** Halogen-free
- AEC-Q200** AEC-Q200

**Series** FA

**Status** Production



Images are for reference only and show exemplary products.

PDF file of this page

Contact

### Documents

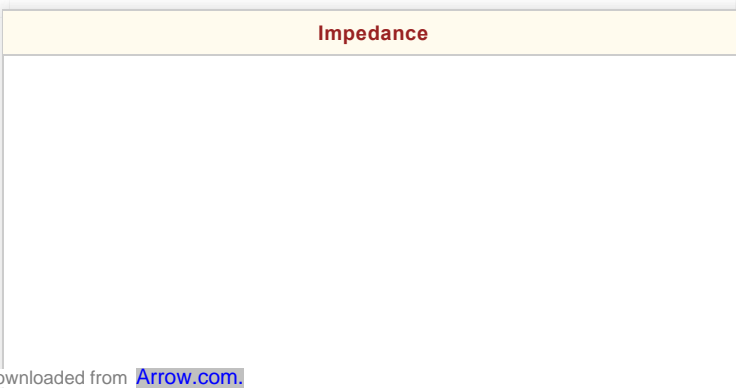
- Catalog
- Specification
- RoHS Certificate
- SVHC/REACH Certificate Update
- [Solution Guide] PCB Deflection Countermeasure / Acoustic Noise Countermeasure / Noise Countermeasures in Automotive DC Motors
- Characterization Sheet

Size	
Length(L)	8.50mm Max.
Width(W)	11.00mm Max.
Thickness(T)	5.50mm Max.
Lead Gap(F)	5.00mm ±1.00mm
Lead Diameter(d)	0.50mm +0.10,-0.03mm

Electrical Characteristics	
Capacitance	22µF ±20%
Rated Voltage	25VDC
Withstanding Voltage	62.5VDC
Temperature Characteristic <span>?</span>	X7R(±15%)
Dissipation Factor (Max.)	3%
Insulation Resistance (Min.)	22MΩ

Other	
Soldering Method	Wave (Flow) Iron Soldering
Lead Length / Package Type	7mm for Bulk
AEC-Q200	Yes
Package Quantity	200pcs

**Characteristic Graph** (This is reference data, and does not guarantee the products characteristics.)



FA23X7R1E226MNU00

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DC Bias Characteristic

FA23X7R1E226MNU00

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Temperature Characteristic

FA23X7R1E226MNU00(No Bias) FA23X7R1E226MNU00(DC Bias = 25 )

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- RF Components and Modules >
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- Sensors and Sensor Systems >
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- Noise Suppressing / Magnetic Sheet >
- Anechoic Chambers and Radio Wave Absorbers >
- Power Supplies >
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- Flash Storages >
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